

2SC4702

Silicon NPN Epitaxial

REJ03G0729-0300
(Previous ADE-208-1120A)

Rev.3.00

Aug.10.2005

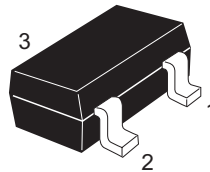
Application

High voltage amplifier

Features

- High breakdown voltage
 $V_{CEO} = 300\text{ V}$
- Small Cob
Cob = 1.5 pF Typ.

Outline

RENESAS Package code: PLSP0003ZB-A
(Package name: MPAK)

1. Emitter
2. Base
3. Collector

Note: Marking is "XV-".

Absolute Maximum Ratings

(Ta = 25°C)

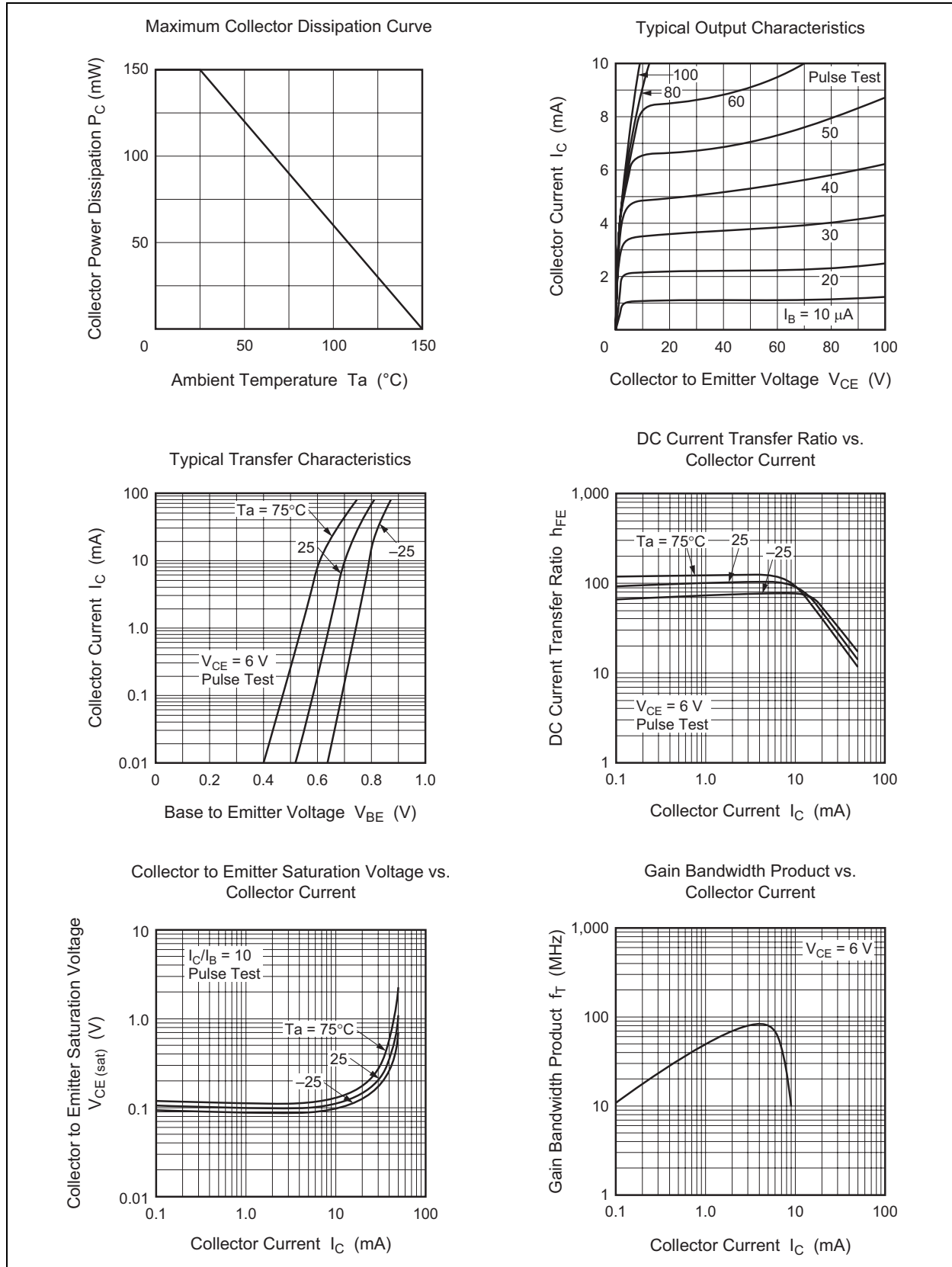
Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	300	V
Collector to emitter voltage	V_{CEO}	300	V
Emitter to base voltage	V_{EBO}	5	V
Collector current	I_C	50	mA
Collector power dissipation	P_C	150	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

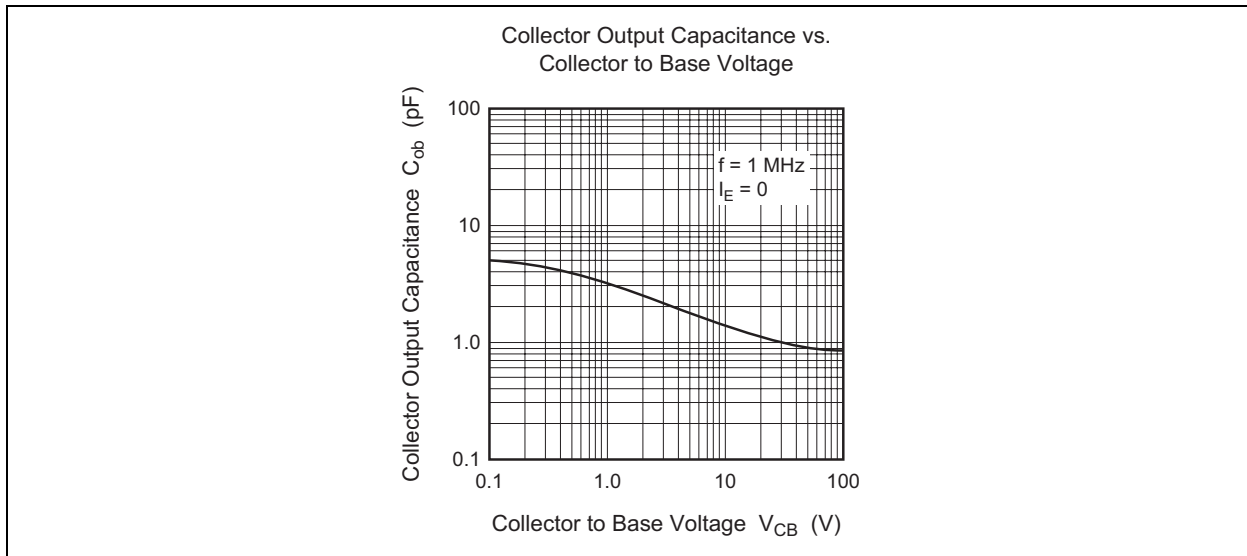
Electrical Characteristics

(Ta = 25°C)

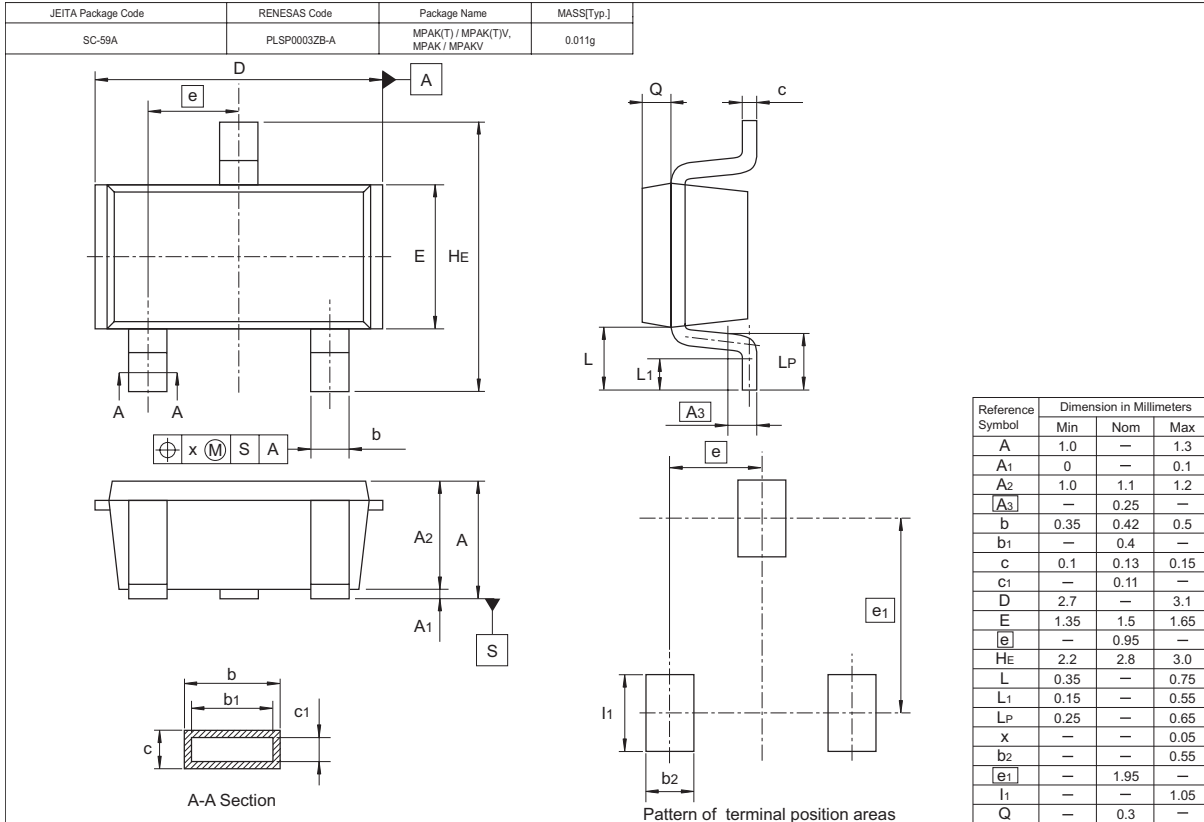
Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	300	—	—	V	$I_C = 10 \mu A, I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	300	—	—	V	$I_C = 1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	5	—	—	V	$I_E = 10 \mu A, I_C = 0$
Collector cutoff current	I_{CBO}	—	—	0.1	μA	$V_{CB} = 250 \text{ V}, I_E = 0$
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	—	0.5	V	$I_C = 30 \text{ mA}, I_B = 3 \text{ mA}$
DC current transfer ratio	h_{FE}	60	—	150		$V_{CE} = 6 \text{ V}, I_C = 2 \text{ mA}$
Gain bandwidth product	f_T	—	80	—	MHz	$V_{CE} = 6 \text{ V}, I_C = 5 \text{ mA}$
Collector output capacitance	C_{ob}	—	1.5	—	pF	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$

Main Characteristics





Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SC4702XV-TR-E	3000	φ 178 mm Reel, 8 mm Emboss Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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